

UNBUMPED LOW CAPACITANCE FLIP CHIP TVS ARRAY

DESCRIPTION

The ULLC0408FC05C Flip Chip employs advanced silicon P/N junction technology for unmatched board-level transient voltage protection against Electrostatic Discharge (ESD) and Electrical Fast Transients (EFT). Developed specifically for high-density circuit protection, this series meets the IEC 61000-4-2 and 61000-4-4 requirements. This low capacitance device is ideally suited for handheld devices, PCMCIA and SMART cards.

The ULLC0408FC05C provides ESD protection greater than 25 kilovolts and features superior clamping performance, low leakage current characteristics and a response time of less than a nanosecond. The low inductance virtually eliminates overshoot voltage due to package inductance.

FEATURES

- Compatible with IEC 61000-4-2 (ESD): Air 15kV, Contact 8kV
- Compatible with IEC 61000-4-4 (EFT): 40A, 5/50ns
- ESD Protection > 25 kilovolts
- Low ESD Overshoot Voltage
- Bidirectional Configuration & Monolithic Structure
- Protects 4 Isolated Lines
- Low Capacitance: 6pF
- Low Leakage Current
- RoHS Compliant
- REACH Compliant

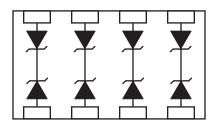
MECHANICAL CHARACTERISTICS

- Standard EIA Chip Size: 0408
- Approximate Weight: 0.73 milligrams
- Lead-Free Plating
- Solder Reflow Temperature:
- Lead-Free Sn/Ag/Cu, 96/3.5/0.5: 260-270°C
- Flammability Rating UL 94V-0
- 8mm Tape per EIA Standard 481

APPLICATIONS

- Cellular Phones
- Portable Electronics
- SMART Cards

PIN CONFIGURATION



TYPICAL DEVICE CHARACTERISTICS

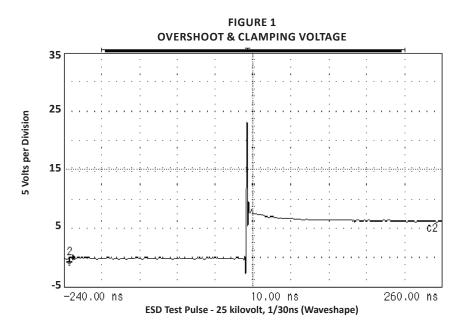
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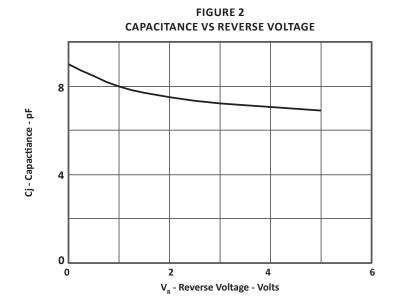
MAXIMUM RATINGS @ 25°C Unless Otherwise Specified								
PARAMETER	VALUE	UNITS						
Operating Temperature	T _A	-55 to 150	°C					
Storage Temperature	T _{stg}	-55 to 150	°C					

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified									
PART NUMBER (Note 1)	RATED STAND-OFF VOLTAGE	MINIMUM BREAKDOWN VOLTAGE	MAXIMUM LEAKAGE CURRENT	TYPICAL CAPACITANCE					
	V _{WM} VOLTS	@ 1mA V _(BR) VOLTS	@V _{wm} Ι _D μΑ	@0V, 1MHz C pF					
ULLC0408FC05C	5.0	6.0	5.0	6					
NOTES 1. Device is bidirectional.									

TYPICAL DEVICE CHARACTERISTICS

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SOLDER REFLOW INFORMATION

PRINTED CIRCUIT BOARD RECOMMENDATIONS							
PARAMETER VALUE							
Pad Size on PCB	0.275mm						
Pad Shape	Round						
Pad Definition	Non-Solder Mask Defined Pads						
Solder Mask Opening	0.325mm Round						
Solder Stencil Thickness	0.150mm						
Solder Stencil Aperture Opening (Laser cut, 5% tapered walls)	0.330mm Round						
Solder Paste Type	No Clean						
Pad Protective Finish	OSP (Entek Cu Plus 106A)						
Tolerance - Edge To Corner Ball	±50µm						
Solder Ball Side Coplanarity (Only applies to bumped devices)	±20µm						
Maximum Dwell Time Above Liquidous (183°C)	60 seconds						
Soldering Maximum Temperature	270°C						

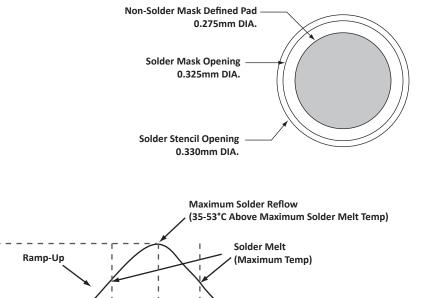
REQUIREMENTS

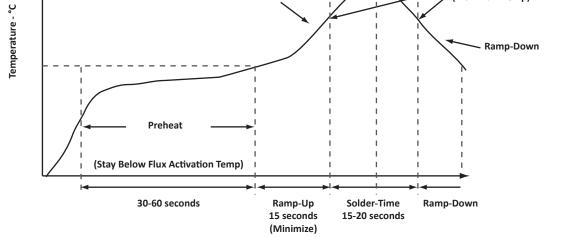
Temperature:

 $T_{\rm p}$ for Lead-Free (Sn/Ag/Cu): 260-270°C Preheat time and temperature depends on solder paste and flux activation temperature, component size, weight, surface area and plating.

T_P

RECOMMENDED NON-SOLDER MASK DEFINED PAD ILLUSTRATION





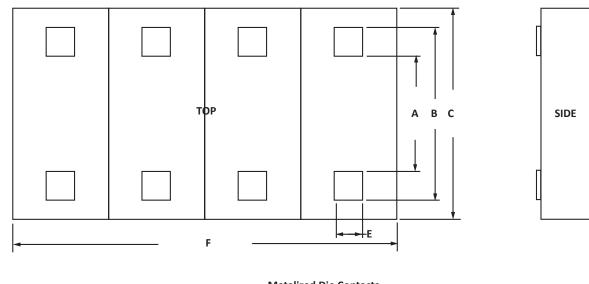
U0408 PACKAGE INFORMATION

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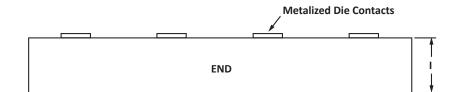
OUTLINE DIMENSIONS									
DIM	MILLIN	IETERS	INCHES						
DIM	MIN MAX MIN M								
А	A 0.56 0.022								
В	0.86 0.034								
С	0.98 1.02 0.038 0.040								
E	E 0.15 SQ 0.006 SQ								
F	1.97	2.03	0.078	0.080					
I 0.406 0.016									
NOTES	NOTES								

1. Controlling dimensions in inches.

2. Decimal tolerance: .xxx ± 0.05mm (0.002").

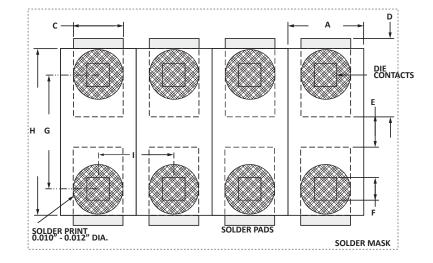






U0408 PACKAGE INFORMATION

OPTION 1 - LAYOUT DIMENSIONS							
DIM	MILLIMETERS	INCHES					
DIN	NOMINAL	NOMINAL					
А	0.51	0.020					
С	0.30	0.012					
D	0.46	0.018					
E	0.20	0.008					
F	0.15 SQ	0.006 SQ					
G	0.71	0.028					
Н	0.99	0.039					
I	0.51	0.020					



NOTES

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1. Controlling dimensions in inches.

2. Decimal tolerance: .xxx \pm 0.05mm (0.002").

3. Preferred: Usign 0.1mm (0.004") stencil.

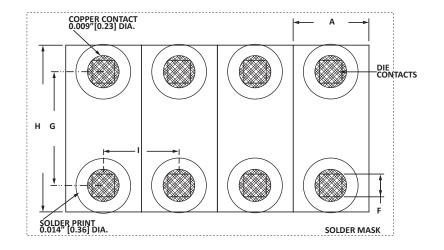
OPTION 2 - LAYOUT DIMENSIONS							
DIM	MILLIMETERS	INCHES					
DIM	NOMINAL	NOMINAL					
А	0.51	0.020					
F	0.15 SQ	0.006 SQ					
G	0.71	0.028					
н	0.99	0.039					
I	0.51	0.020					
H							

NOTES

1. Controlling dimensions in inches.

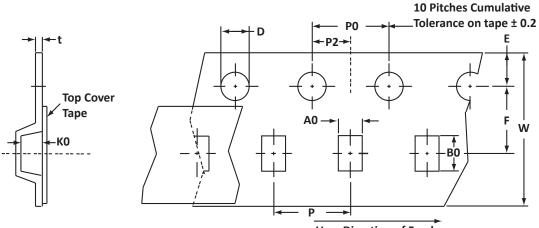
2. Decimal tolerance: .xxx ± 0.05mm (0.002").

3. Preferred: Usign 0.1mm (0.004") stencil.



TAPE AND REEL INFORMATION

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User Direction of Feed

REEL DIA. TAPE WIDTH A0 B0 K0 D E F W P0 P2 P Tmax 178(7") 8 0.80 ± 0.10 1.20 ± 0.10 0.70 ± 0.10 1.50 ± 0.10 1.75 ± 0.10 3.50 ± 0.05 8.00 ± 0.20 4.00 ± 0.12 2.00 ± 0.05 2.00 ± 0.10 0.25 NOTES I. Dimensions in millimeters. I. Orientation: preferred stencil - 0.1mm (0.004"). K K K K E F W P0 P2 P Tmax 3. Orientation: preferred stencil - 0.1mm (0.004"). 4.00 ± 0.12 2.00 ± 0.05 2.00 ± 0.10 0.25 4. Surface mount product is taped and reeled in accordance with EIA 481. 5. 8mm plastic tape: 7" Reels - 5,000 Image: Color and Lot Number. Image: Color and Lot Number.	SPECIFICATIONS												
NOTES TAPE & REEL ORIENTATION 1. Dimensions in millimeters. 2. Top view of tape. Metal contacts are face down in tape package. 3. Orientation: preferred stencil - 0.1mm (0.004"). 4. Surface mount product is taped and reeled in accordance with EIA 481. 5. 8mm plastic tape: 7" Reels - 5,000 6. Marking on reel: Part Number, Date Code and Lot Number.	REEL DIA.		A0	В0	ко	D	E	F	w	PO	P2	Р	Tmax
 1. Dimensions in millimeters. 2. Top view of tape. Metal contacts are face down in tape package. 3. Orientation: preferred stencil - 0.1mm (0.004"). 4. Surface mount product is taped and reeled in accordance with EIA 481. 5. 8mm plastic tape: 7" Reels - 5,000 6. Marking on reel: Part Number, Date Code and Lot Number. 	178(7")	8	0.80 ± 0.10	1.20 ± 0.10	0.70 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.20	4.00 ± 0.12	2.00 ± 0.05	2.00 ± 0.10	0.25
	 Dimensions in m Top view of tape Orientation: pre Surface mount p 8mm plastic tap 	e. Metal cont ferred stenci product is tap e: 7" Reels -	l - 0.1mm (0.0 oed and reeled 5,000	04"). in accordance	with EIA 481.				TAPE &			N	

ORDERING INFORMATION								
BASE PART NUMBER LEADFREE SUFFIX TAPE SUFFIX QTY/REEL REEL SIZE TUBE QTY								
ULLC0408FC05C	n/a	-T75-1	5,000	7"	n/a			

COMPANY INFORMATION

COMPANY PROFILE

ProTek Devices, based in Tempe, Arizona USA, is a manufacturer of Transient Voltage Suppression (TVS) products designed specifically for the protection of electronic systems from the effects of lightning, Electrostatic Discharge (ESD), Nuclear Electromagnetic Pulse (NEMP), inductive switching and EMI/RFI. With over 25 years of engineering and manufacturing experience, ProTek designs TVS devices that provide application specific protection solutions for all electronic equipment/systems.

ProTek Devices Analog Products Division, also manufactures analog interface, control, RF and power management products.

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PATENT INFORMATION: This device is patented under U.S. Patent No. Des. "D456,367S".